



Tessolve Joins STMicroelectronics Partner Program as an engineering solution partner to provide HW/SW/System services and solutions to customers.

Bangalore, 8th January 2021 – Tessolve, a Hero Electronix venture and an end-to-end engineering solutions partner for semiconductor and product companies, announces that it has joined the STMicroelectronics Partner Program for providing HW/SW/System services and solutions that leverage the best of the ST portfolio, including a wide selection of STM32 Microcontrollers/Microprocessors, Micro-Electro-Mechanical (MEMS) sensors and actuators, connectivity products, and AI and embedded applications development tools..

Joining ST's robust partner program, Tessolve is poised to provide design services based on the ST portfolio to further the capabilities and resources with its expertise in original equipment design, manufacturing, and qualification to meet the rapidly growing needs of OEMs globally.

Tessolve is also a leading ODC provider of innovative services for semiconductors, embedded systems and specific SW applications for integrated circuits that comprise the essential building blocks of Internet of Things (IoT) edge devices by delivering the network nodes that enable practical and scalable IoT systems. Building on its strong heritage in embedded computing, Tessolve provides the hardware including advanced software capabilities and multi-standard connectivity required in end-to-end IoT business solutions. Tessolve reduces the complexity and helps speed the deployment of IoT systems that liberate data from sensors to the cloud, thus enabling new business models for our customers and partners.

As Mr. KP Jagadeesha says, Vice President Embedded Systems: *“Becoming an Authorized ST Partner is the natural continuity of our strong, long-term relationship with ST where we provide upstream support in the design activities of their many semiconductor solutions. This allows Tessolve to more quickly implement the ST technologies into IoT and Automotive product developments with the best processing, connectivity and AI performance, optimized for the end customers applications”.*

“The ST Partner Program helps customers’ design teams access extra skills and resources to aid engineering development and shorten time-to-market for new products,” said Alessandro Maloberti, Partner Ecosystem Director, STMicroelectronics. *“By selecting, qualifying, and certifying our program partners, we are taking yet another major step in helping customers accelerate design and development, and ship to market the most robust and efficient products and services.”*

STMicroelectronics, a global semiconductor leader serving customers across the spectrum of electronics applications created the ST Partner Program to speed customer development efforts by identifying and highlighting to them companies with complementary products and services. Moreover, the program's certification process assures that all partners are periodically vetted for quality and competence. For more information, please visit www.st.com/partners

About Tessolve

Tessolve (a Hero Electronix Venture), with 2200+ employees worldwide, is the market leader in providing engineering solutions for silicon and systems development. We offer a unique combination of both pre-silicon and post-silicon expertise to provide an efficient turnkey solution for silicon bring up, spec to a product.

Tessolve enables customers a faster time-to-market through deep domain expertise in Analog, Digital, Mixed Signal, and RF, broad ATE platform experience, diverse embedded software services and built-in infrastructure including a test floor, characterization, reliability lab, system lab and PCB FAB.

Tessolve delivers ASIC design services including advanced process nodes with a strong eco-system relationship with EDA, IP, and foundries. Tessolve's post-silicon solution takes silicon from the foundry to high volume manufacturing. Our front-end design strengths integrated with the knowledge from the backend flow, allows Tessolve to catch design flaws ahead in the cycle, thus reducing expensive re-design costs, and risks.

Tessolve offers end-to-end product design services in the embedded domain from concept-to-manufacturing under an ODM model with experience in IoT & multimedia products for the Avionics, Automotive, Industrial and Medical segments. Tessolve's solution includes system design, hardware, and mechanical development, BSP and firmware development, Middleware integration, third party application integration, application development, testing, validation & certification/qualification, production management and product cycle support. Tessolve delivers value by customizing the platform, including HMI and mechanical enclosure.

Tessolve partners with customers to make great ideas into great products.

Please visit https://www.st.com/content/st_com/en/partner/partner-program/partnerpage/Tessolve.html

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